| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|--|------------|------------|
| 1 | 417 | 438/689,690.ccls. | USPAT | 2002/12/24 |
| | | | İ | 11:43 |
| 2 | 1330 | 438/691,692.ccls. | USPAT | 2002/12/24 |
| | | | | 11:52 |
| 3 | 1034 | 438/693,694.ccls. | USPAT | 2002/12/24 |
| | | | | 11:43 |
| 4 | 521 | 438/695,697.ccls. | USPAT | 2002/12/24 |
| | | , | JOI A. | 11:44 |
| 5 | 1053 | lee-young\$.in. kim-tae\$.in. kim-jin\$.in. | USPAT | 2002/12/24 |
| | | an-jung\$.in. song-jong\$.in. | OO! A! | 11:46 |
| 6 | 333 | lee-young\$.in. kim-tae\$.in. kim-jin\$.in. | US-PGPUB | 2002/12/24 |
| · · | | an-jung\$.in. song-jong\$.in. | U3-FGFUB | |
| 7 | 892 | lee-young\$.in. kim-tae\$.in. kim-jin\$.in. | FDG. IDG | 11:47 |
| ' | 032 | | EPO; JPO; | 2002/12/24 |
| | I | an-jung\$.in. song-jong\$.in. | DERWENT; | 11:47 |
| _ | 04504 | | IBM_TDB | |
| 8 | 31721 | (planar\$8 "cmp" "CMP" polish\$3) and | USPAT | 2002/12/24 |
| | | (substrate wafer) and (photoresist resist) | | 11:57 |
| 9 | 20079 | ((planar\$8 "cmp" "CMP" polish\$3) and | USPAT | 2002/12/24 |
| | | (substrate wafer) and (photoresist resist)) | | 11:55 |
| | | and ((planar\$8 "cmp" "CMP" polish\$3) same | | |
| | | (substrate wafer)) | | |
| 10 | 4461 | (((planar\$8 "cmp" "CMP" polish\$3) and | USPAT | 2002/12/24 |
| | | (substrate wafer) and (photoresist resist)) | | 12:00 |
| | ļ | and ((planar\$8 "cmp" "CMP" polish\$3) same | | |
| | | (substrate wafer))) and ((planar\$8 "cmp" | | |
| | | "CMP" polish\$3) adj2 (substrate wafer)) | İ | |
| 11 | 3657 | ((((planar\$8 "cmp" "CMP" polish\$3) and | USPAT | 2002/12/24 |
| 1 | | (substrate wafer) and (photoresist resist)) | JOIAI | 11:56 |
| | | and ((planar\$8 "cmp" "CMP" polish\$3) same | | 11:30 |
| | | (substrate wafer))) and ((planar\$8 "cmp" | | |
| | | "CMP" polish\$3) adj2 (substrate wafer))) and | | |
| | | | | |
| 40 | 2544 | (etch\$3 same (layer film)) | | |
| 12 | 3514 | (((((planar\$8 "cmp" "CMP" polish\$3) and | USPAT | 2002/12/24 |
| | 1 | (substrate wafer) and (photoresist resist)) | | 12:01 |
| 1 | | and ((planar\$8 "cmp" "CMP" polish\$3) same | | 1 |
| | | (substrate wafer))) and ((planar\$8 "cmp" | | |
| | Ì | "CMP" polish\$3) adj2 (substrate wafer))) and | | |
| | | (etch\$3 same (layer film))) and ((photoresist | | |
| | | resist) same (wafer film layer substrate)) | | |
| 13 | 1135 | ((((((planar\$8 "cmp" "CMP" polish\$3) and | USPAT | 2002/12/24 |
| | | (substrate wafer) and (photoresist resist)) | | 12:01 |
| | | and ((planar\$8 "cmp" "CMP" polish\$3) same | | |
| Ì | | (substrate wafer))) and ((planar\$8 "cmp" | | |
| | | "CMP" polish\$3) adj2 (substrate wafer))) and | | |
| | | (etch\$3 same (layer film))) and ((photoresist | | |
| | | resist) same (wafer film layer substrate))) | | |
| | | and ((planar\$8 "cmp" "CMP" polish\$3) adj2 | | |
| | | (layer film)) | | |
| 4 | 6965 | , , | 5 0 | 000045/54 |
| ~ | 0303 | ((planar\$8 "cmp" "CMP" polish\$3) adj2 (layer | EP ; JP ; | 2002/12/24 |
| _ | | film)) | DERWENT; | 12:02 |

| 15 | 634 | (((planar\$8 "cmp" "CMP" polish\$3) adj2 | EP ; JP ; | 2002/12/24 |
|----|------|--|-----------|------------|
| | | (layer film))) and ((photoresist resist) same | DERWENT: | 12:02 |
| | | (wafer film layer substrate)) | IBM TDB | |
| 16 | 3021 | ((planar\$8 "cmp" "CMP" polish\$3) adj2 (layer | US-PGPUB | 2002/12/24 |
| | | film)) | | 12:02 |
| 17 | 1470 | (((planar\$8 "cmp" "CMP" polish\$3) adj2 | US-PGPUB | 2002/12/24 |
| | Ē. | (layer film))) and ((photoresist resist) same | | 12:02 |
| | | (wafer film layer substrate)) | | |